



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Koning et al.

NANOTUBE MODIFIED SOLDER THERMAL INTERMEDIATE STRUCTURE, SYSTEMS,
AND METHODS

Docket No.: 884.863US1

Serial No.: 10/747927

Filed: December 30, 2003

Due Date: N/A

Examiner: Unknown

Group Art Unit: Unknown

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

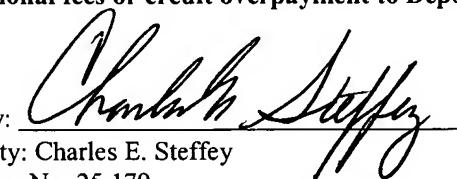
We are transmitting herewith the following attached items (as indicated with an "X"):

- A return postcard.
- A Communication Concerning Related Applications (2 pgs.).
- A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 3 cited documents (Copies of US Patent/Publication documents NOT enclosed, application filed after June 30, 2003).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: 
Atty: Charles E. Steffey
Reg. No. 25,179

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KACIA LEE

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Kacia Lee

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



10/747927

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Paul A. Koning et al.	Examiner:	Unknown
Serial No.:	10/747927	Group Art Unit:	Unknown
Filed:	December 30, 2003	Docket:	884.863US1
Title:	NANOTUBE MODIFIED SOLDER THERMAL INTERMEDIATE STRUCTURE, SYSTEMS, AND METHODS		
Assignee:	Intel Corporation	Customer No.:	21186

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/170313	June 12, 2002	884.564US1	INCREASING THERMAL CONDUCTIVITY OF THERMAL INTERFACE USING CARBON NANOTUBES AND CVD
10/024057	December 17, 2001	884.569US1	METHOD AND APPARATUS FOR PRODUCING ALIGNED CARBON NANOTUBE THERMAL INTERFACE STRUCTURE
10/738637	December 16, 2003	884.564US2	INCREASING THERMAL CONDUCTIVITY OF THERMAL INTERFACE USING CARBON NANOTUBES AND CVD

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/747927

Filing Date: December 30, 2003

Title: NANOTUBE MODIFIED SOLDER THERMAL INTERMEDIATE STRUCTURE, SYSTEMS, AND METHODS

Assignee: Intel Corporation

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Dkt: 884.863US1

Respectfully submitted,

PAUL A. KONING ET AL.

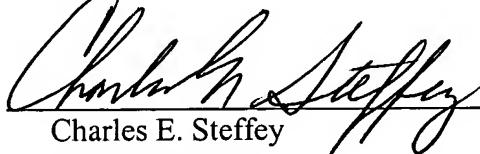
By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date

April 28, 2004

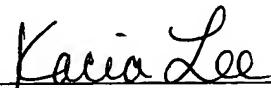
By


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Signature



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